

P-Channel 40-V (D-S), 175 °C MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^a	Q _g (Typ.)
- 40	0.023 at V _{GS} = 10 V	- 20	20.6 nC
	0.030 at V _{GS} = 4.5 V	- 20	

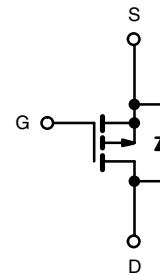
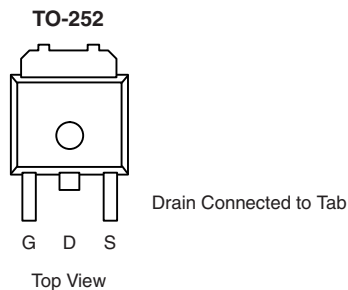
FEATURES

- TrenchFET[®] Power MOSFET
- 100 % R_g Tested


RoHS
COMPLIANT

APPLICATIONS

- LCD TV Inverter



P-Channel MOSFET

Ordering Information: SUD50P04-23-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted				
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V _{DS}	- 40	V	
Gate-Source Voltage	V _{GS}	± 16		
Continuous Drain Current (T _J = 150 °C)	I _D	T _C = 25 °C	- 20 ^a	A
		T _C = 100 °C	- 20 ^a	
		T _A = 25 °C	- 8.2 ^b	
		T _A = 100 °C	- 5.7 ^b	
Pulsed Drain Current	I _{DM}	- 50		
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C	- 20 ^a	
		T _A = 25 °C	- 2.5 ^b	
Single Pulse Avalanche Current	I _{AS}	- 20		
Avalanche Energy	E _{AS}	20	mJ	
Maximum Power Dissipation	P _D	T _C = 25 °C	45.4	W
		T _C = 100 °C	22.7	
		T _A = 25 °C	3.1 ^b	
		T _A = 100 °C	1.5 ^b	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to 175	°C	

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	R _{thJA}	40	48	°C/W	
Maximum Junction-to-Case	R _{thJC}	2.75	3.3		

Notes:

a. Package limited.

b. Surface mounted on 1" x 1" FR4 board.

SPECIFICATIONS $T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0\text{ V}, I_D = -250\text{ }\mu\text{A}$	-40			V
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\text{ }\mu\text{A}$		-40		mV/ $^\circ\text{C}$
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		3.7			
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\text{ }\mu\text{A}$	-0.8		-2	V
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\text{ V}, V_{GS} = \pm 16\text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -40\text{ V}, V_{GS} = 0\text{ V}$			-1	μA
		$V_{DS} = -40\text{ V}, V_{GS} = 0\text{ V}, T_J = 100\text{ }^\circ\text{C}$			-20	
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq -5\text{ V}, V_{GS} = -10\text{ V}$	-30			A
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -10\text{ V}, I_D = -15\text{ A}$		0.019	0.023	Ω
		$V_{GS} = -4.5\text{ V}, I_D = -10\text{ A}$		0.024	0.030	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}, I_D = -15\text{ A}$		30		S
Dynamic^b						
Input Capacitance	C_{iss}	$V_{DS} = -20\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$		1880		pF
Output Capacitance	C_{oss}		286			
Reverse Transfer Capacitance	C_{rss}		192			
Total Gate Charge	Q_g	$V_{DS} = -20\text{ V}, V_{GS} = -10\text{ V}, I_D = -30\text{ A}$		43.5	65	nC
				20.6	31	
Gate-Source Charge	Q_{gs}	$V_{DS} = -20\text{ V}, V_{GS} = -4.5\text{ V}, I_D = -30\text{ A}$		4.6		nC
Gate-Drain Charge	Q_{gd}			7.6		
Gate Resistance	R_g		$f = 1\text{ MHz}$		3	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -20\text{ V}, R_L = 0.66\text{ }\Omega$ $I_D \cong -30\text{ A}, V_{GEN} = -4.5\text{ V}, R_g = 1\text{ }\Omega$		22	35	ns
Rise Time	t_r			217	325	
Turn-Off Delay Time	$t_{d(off)}$			42	65	
Fall Time	t_f			21	32	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -20\text{ V}, R_L = 0.66\text{ }\Omega$ $I_D \cong -30\text{ A}, V_{GEN} = -10\text{ V}, R_g = 1\text{ }\Omega$		8	15	
Rise Time	t_r			12	20	
Turn-Off Delay Time	$t_{d(off)}$			36	55	
Fall Time	t_f			9	15	
Drain-Source Body Diode Characteristics						
Continuous Source-Drain Diode Current	I_S	$T_C = 25\text{ }^\circ\text{C}$			-20	A
Pulse Diode Forward Current ^a	I_{SM}				-50	
Body Diode Voltage	V_{SD}	$I_S = -10\text{ A}$		-0.85	-1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$		44	66	ns
Body Diode Reverse Recovery Charge	Q_{rr}			53	80	nC
Reverse Recovery Fall Time	t_a			18		ns
Reverse Recovery Rise Time	t_b			26		

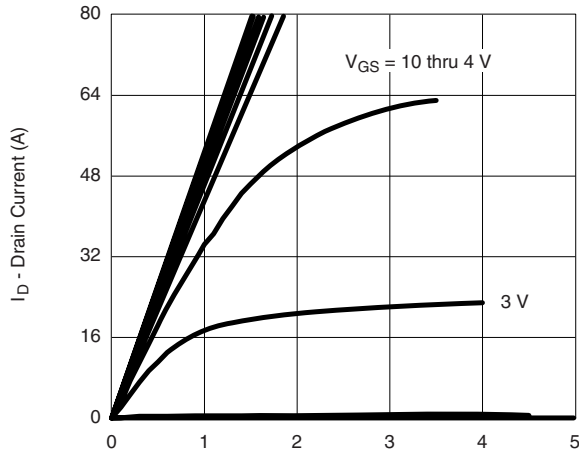
Notes:

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$.
b. Guaranteed by design, not subject to production testing.

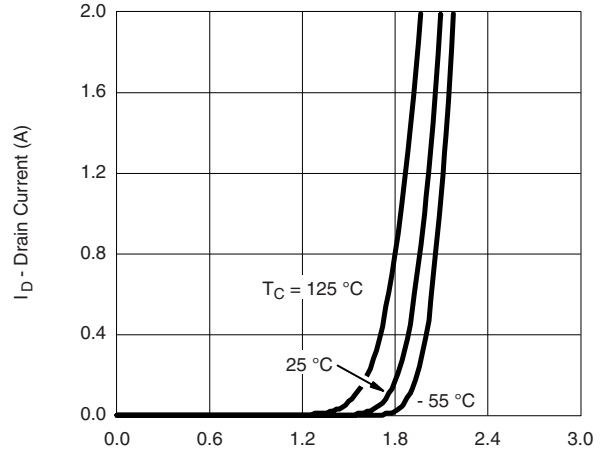
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



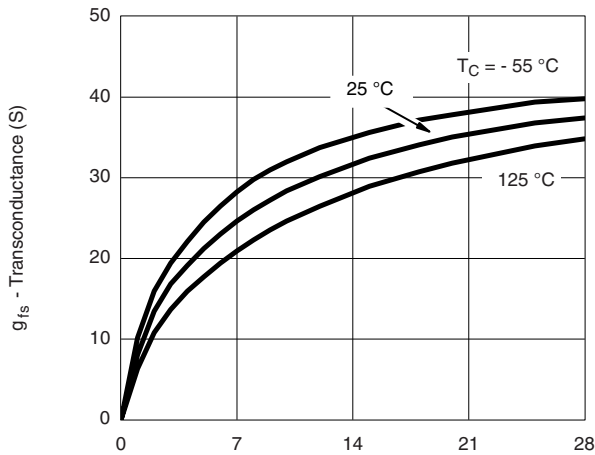
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



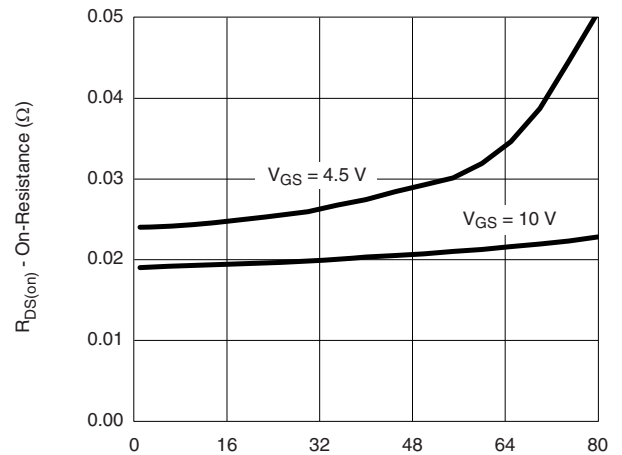
Output Characteristics



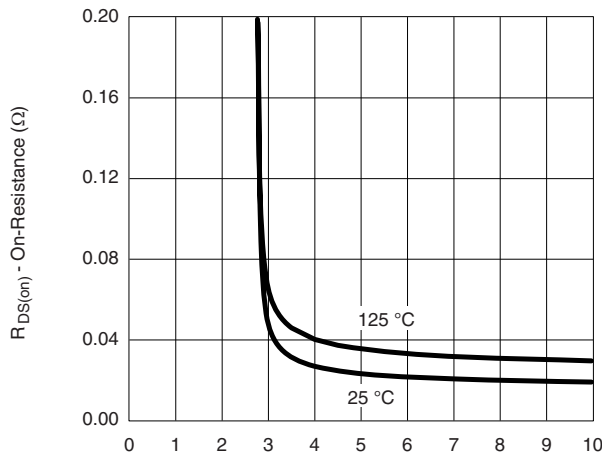
Transfer Characteristics



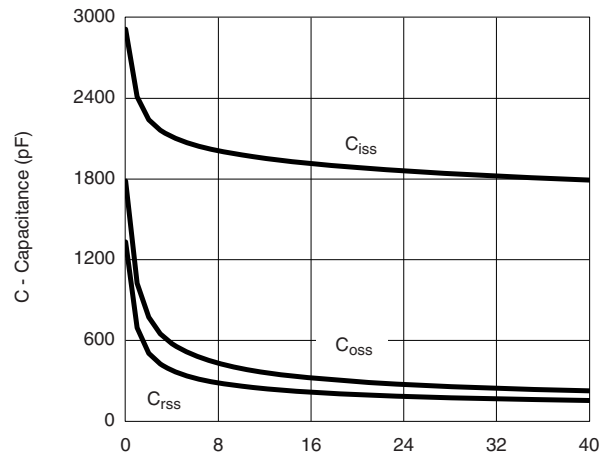
Transconductance



On-Resistance vs. Drain Current

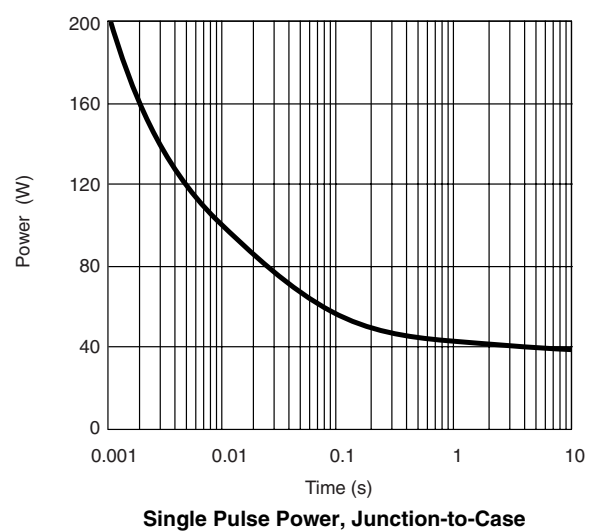
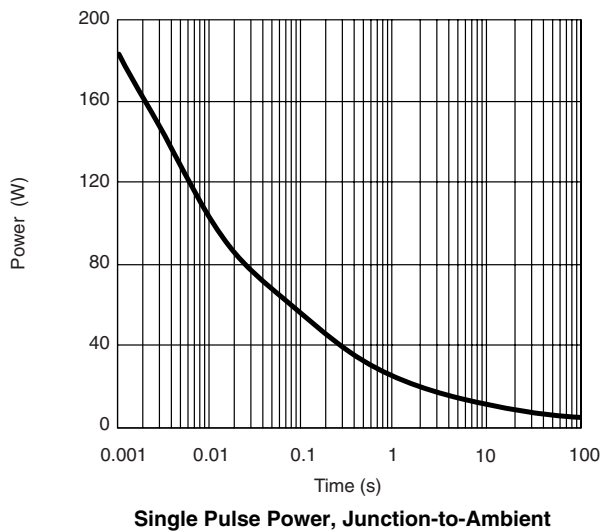
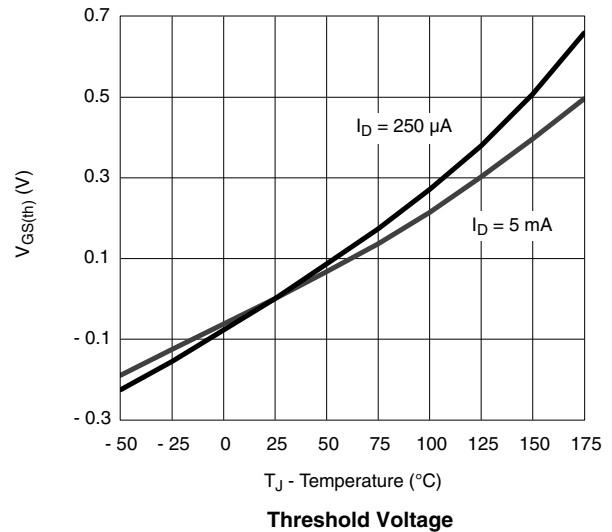
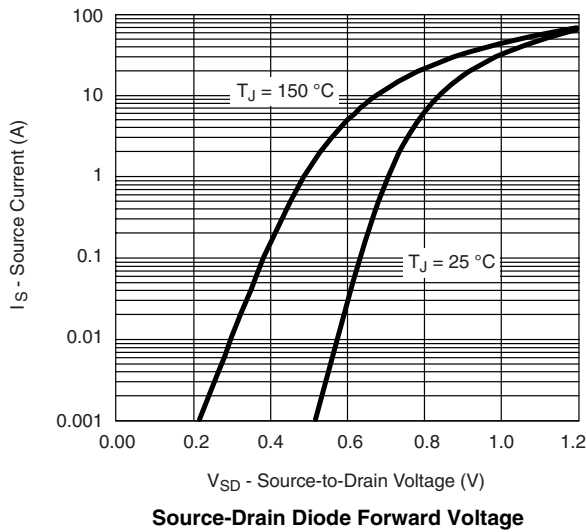
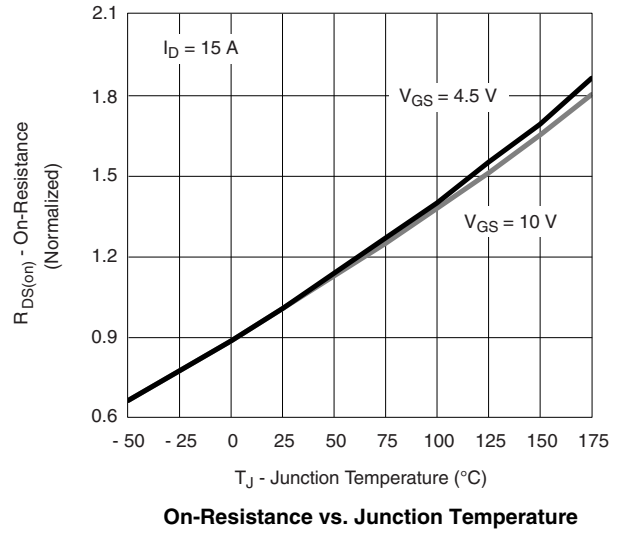
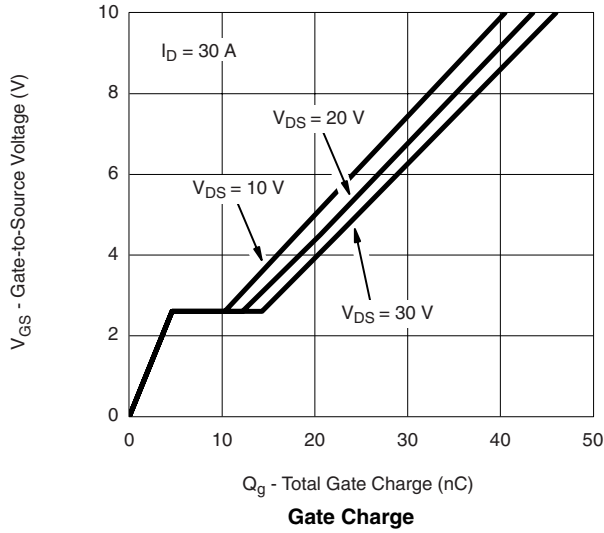


On-Resistance vs. Gate-to-Source Voltage

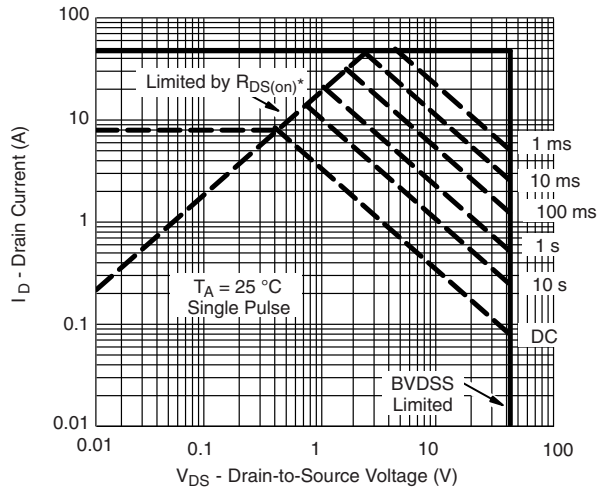


Capacitance

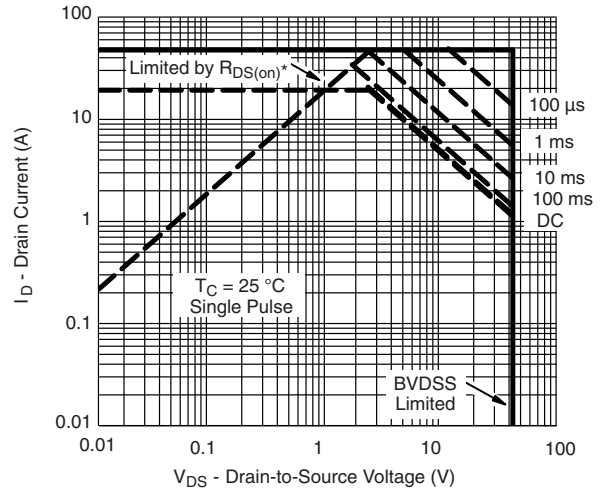
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



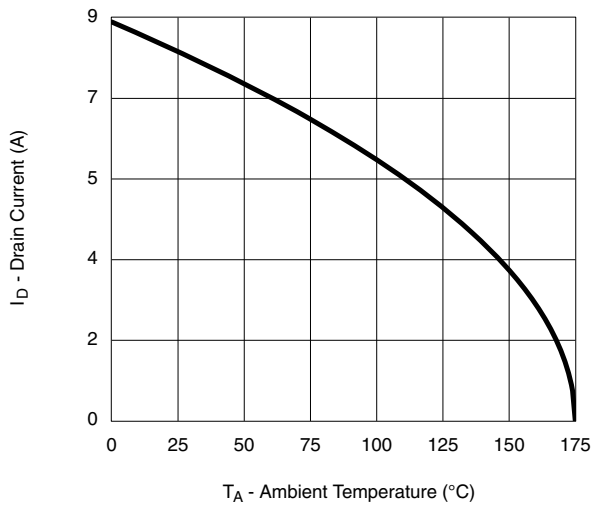
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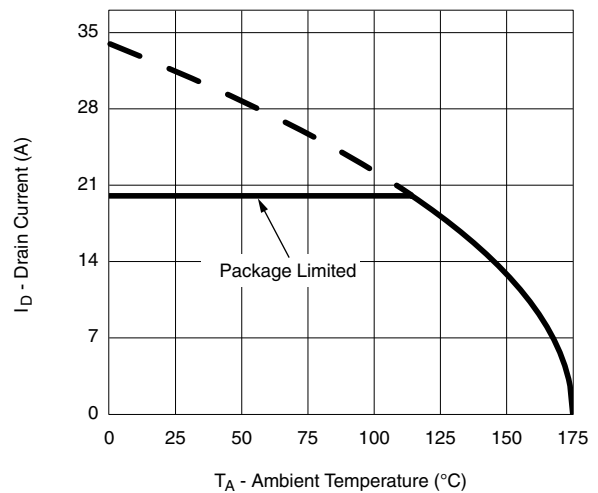
* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified
Safe Operating Area, Junction-to-Ambient



* $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified
Safe Operating Area, Junction-to-Case



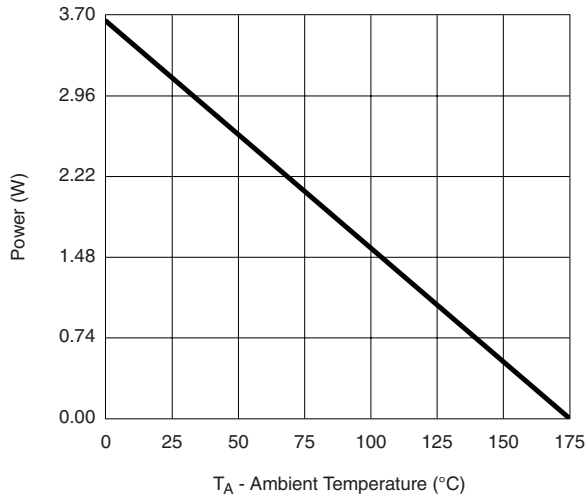
Current Derating, Junction-to-Ambient**



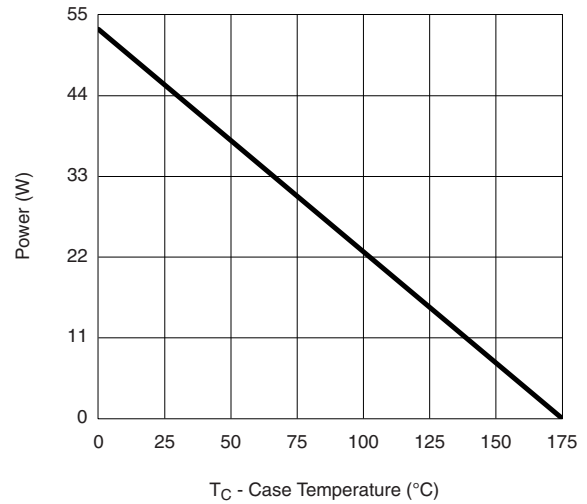
Current Derating, Junction-to-Case**

** The power dissipation P_D is based on $T_{J(max)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



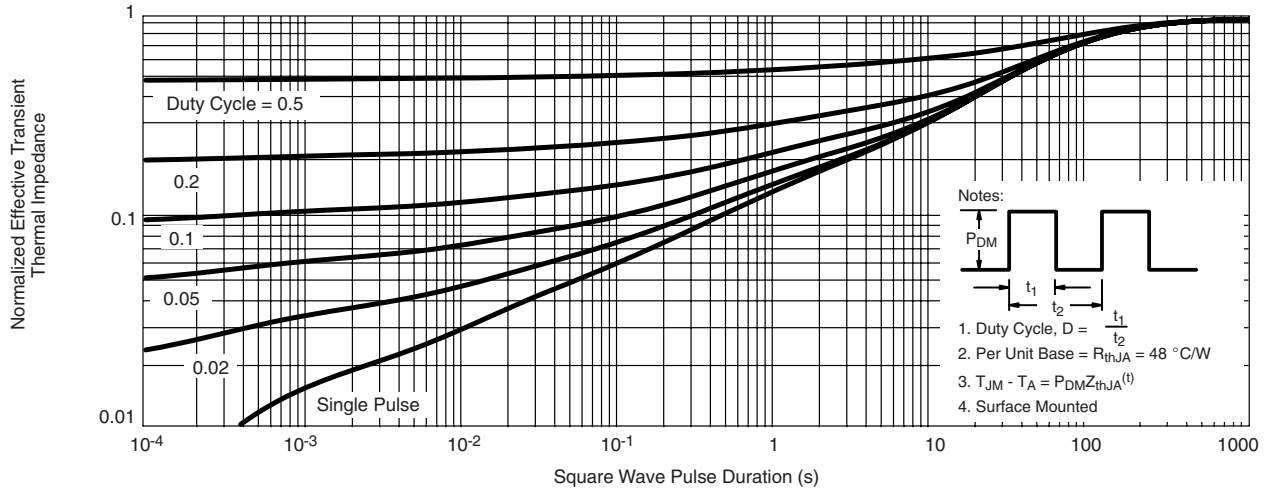
Power Derating*, Junction-to-Ambient



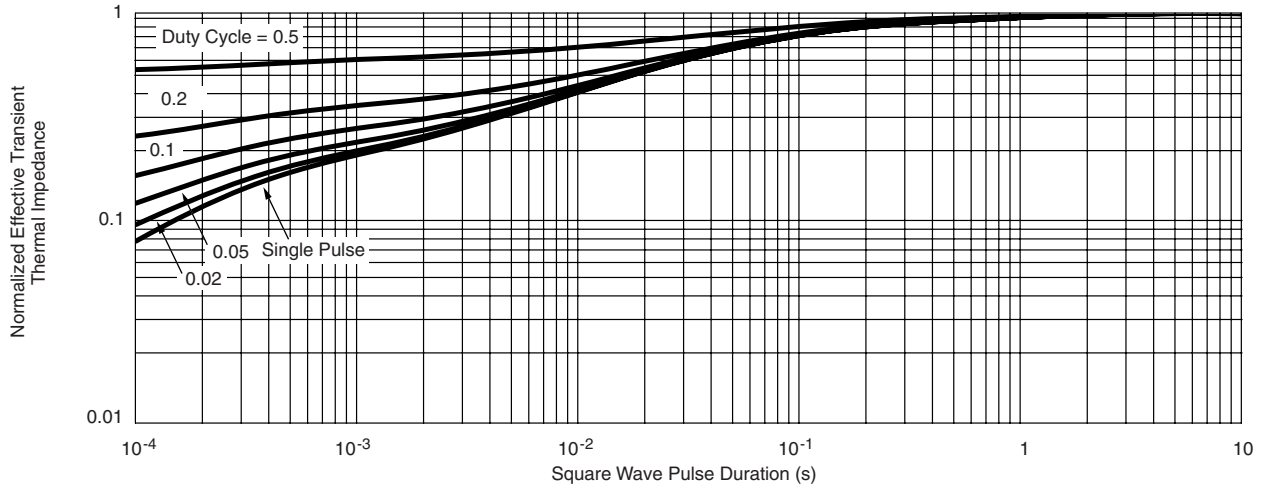
Power Derating*, Junction-to-Case

* The power dissipation P_D is based on $T_{J(max)} = 175\text{ °C}$, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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